



Package Change for the Virtex-II Pro Devices

XCN05012 (v1.0) August 1, 2005

Product/Process Change Notice

Overview

The purpose of this notification is to communicate a package layer change for Virtex™-II Pro devices.

Description

As part of the Xilinx material standardization process, and to enhance signal integrity, the Virtex-II Pro family devices (listed below) in the flip-chip package are changing to an 8-layer package material set. This change is backward-compatible with the 6-layer package that is currently shipping in production.

Products Affected

This change applies to the C and I temperature grades and all speed grades of the XC2VP30-FF896, XC2VP30-FF1152, XC2VP70-FF1704, and XC2VP100-FF1704.

Key Dates

Please see the table below for sample availability and targeted production switch dates. Production samples of the new 8-layer package for the XC2VP30-FF1152 and the XC2VP70-FF1704 devices are currently available.

The XC2VP30-FF896 and the XC2VP100-FF1704 8-layer package production samples will be available as shown in the table below. The 8-layer package can be ordered during the transition period for sample or production use by specifying SCD0966. To use SCD0966, append "0966" to the end of the standard ordering part number (e.g., XC2VP70-6FF1704C**0966**). On each production switch date SCD0966 will be discontinued. Until the 6-layer inventory is depleted, Xilinx will cross-ship either the 6-layer package device or the 8-layer package device as the standard part number.

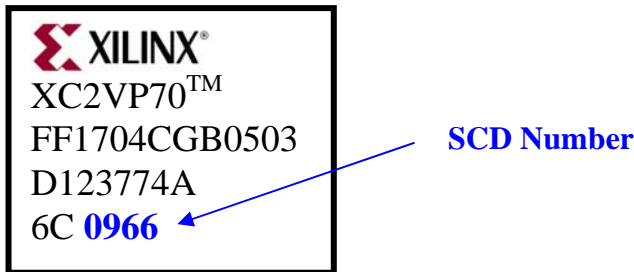
Device	SCD for 8 layer package device	Sample Availability	Production Switch
XC2VP30-FF896	SCD0966	November 1, 2005	February 1, 2006
XC2VP30-FF1152	SCD0966	August 1, 2005	November 1, 2005
XC2VP70-FF1704	SCD0966	August 1, 2005	November 1, 2005
XC2VP100-FF1704	SCD0966	February 1, 2006	May 1, 2006

Qualification Data

Qualification data for the 8-layer package device is available in the [Virtex-II Pro 8-Layer Package Substrate Report](#).

Traceability

Until the production switch date, devices using the 8-layer package can be visually identified by SCD number “0966” marked on the 4th line of the package top-mark. At a later date, a date code will be provided to identify the 8-layer package.



Recommendation

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Revision History

The following table shows the revision history for this document.

Date	Version	Revision
8/01/05	1.0	Initial release.